

	Room A	Room B	Room C	Room D	Room E	Room F	
8:30 9:15			Keynote Lecture III: Advanced Thinning and Cutting Technologies Enabling AI-Oriented Heterogeneous Integration Younseok Kim, DISCO Corp.				
Break							
9:30	16TA1: Glass PKG-1 16TA1-1 <Session Invited> Opportunities and Challenges of Glass Core Substrate Technologies Andreas Oestmann, Fraunhofer IZM 16TA1-2 <Session Invited> A Panel-Level Manufacturing Platform for Reliable Glass Core Substrates for Next Generation IC Packages Christian Buchner, SCHMID Group 16TA1-3 Glasses as substrates for packaging: Remarks on Mechanic reliability connected to via-via distance and via density. Martin Letz ¹ , Fabian Wagner ¹ , Inge Burger ¹ , Vanessa Glaeser ¹ , Volker Seibert ¹ , Ulrich Peuchert ¹ , SCHOTT AG, SCHOTT Semicon glass solutions 16TA1-4 From Via to Singulation - Laser Technologies Driving Glass-Based Advanced Packaging Nils Anspach, Daniel Dunker, Jannis Heinz, Simon Hirt, Norbert Ambrosius, Roman Ostholz, LPKF Laser and Electronics SE	16TB1: ISMP-1 16TB1-1 <Session Invited> Bonding Strength Enhancement in Cu/SiO ₂ Hybrid Bonding Prof. Sungdon Kim, Department of Mechanical System Design Engineering, Seoul National University of Science and Technology 16TB1-2 <Session Invited> Understanding the interfacial reactions between dielectrics and dielectrics for hybrid bonding applications Prof. Changwan Choi, Division of Materials Science and Engineering, Hanyang University 16TB1-3 <Session Invited> Anisotropic Conductive Adhesive for Assembly of Microchips Tae-il Kim, School of Chemical Engineering, Sungkyunkwan University 16TB1-4 <Session Invited> Silicon Integrity Challenges and Opportunities in High-Density Chiplet I/O on Glass Substrates Jimin Kwon, School of Chemical Engineering, Sungkyunkwan University	16TC1: Ceramic Solution 16TC1-1 Feasibility study of laterally embedded ceramic inlays into Silicon substrates for sensor applications Michael Fischer, Cathleen Kleinholz, Björn Mueller, Alexander Schulz, Jens Mueller, Ilmenau Technical University, Electronics Technology Group 16TC1-2 Silicon on Ceramic an Innovative Technology Platform Cathleen Kleinholz ² , Björn Mueller ² , Michael Fischer ² , Alexander Schulz ² , Andrea Cyriax ² , Michael Hintz ² , Thomas Orlepp ² , Jens Mueller ² , ² Technische Universität Ilmenau, ² CIS Forschungsinstitut für Mikrosensorik GmbH 16TC1-3 Impact of Surface Treatment Queue Time on Low-Temperature Nencystalline Cu Bonding Chen-Ning Li ¹ , Artur Kolcis ¹ , Mengning Li ¹ , Shantian Ghongshui ¹ , Jiafeng Jiang ¹ , Tien-Jen Cheng ¹ , Chih Chen ¹ , National Yang Ming Chiao Tung University, Lam Research Corporation 16TD1-4 In-Sn Passivated Low Temperature and Low Pressure fine-pitch Cu-Cu Interconnects Yu-Hsiang Lu ¹ , Po-Shao Shih ¹ , Wei-Chong Lee ¹ , Cheng-Ya Yang ¹ , Yun-Ching Hung ¹ , Yung-Sheng Lin ¹ , Chen-Chao Wang ¹ , Chin-Pin Hung ¹ , C. Kao ¹ , Department of Materials Science and Engineering, National Taiwan University, Advanced Semiconductor Engineering, Inc., Taiwan	16TD1: Cu-Cu Bonding 16TD1-1 Electrodeposited Oriented Nanotwined Cu for Low Temperature Hybrid Bonding Yunwen Wu ¹ , Xingya Pan ¹ , Wenfeng Huang ¹ , Yuhang Li ¹ , Shenghong Ju ¹ , School of Material Science and Engineering, Shanghai Jiaotong University, ¹ Key Laboratory for Thermal Science and Power Engineering of Ministry of Education, Department of Engineering Mechanics, Tsinghua University 16TD1-2 A designed (110)-oriented twin structure for low temperature Cu-Cu bonding Shichen Xie, Zishan Xiong, Yingxia Liu, City University of Hong Kong 16TD1-3 Impact of Surface Treatment Queue Time on Low-Temperature Nencystalline Cu Bonding Chen-Ning Li ¹ , Artur Kolcis ¹ , Mengning Li ¹ , Shantian Ghongshui ¹ , Jiafeng Jiang ¹ , Tien-Jen Cheng ¹ , Chih Chen ¹ , National Yang Ming Chiao Tung University, Lam Research Corporation 16TD1-4 In-Sn Passivated Low Temperature and Low Pressure fine-pitch Cu-Cu Interconnects Yu-Hsiang Lu ¹ , Po-Shao Shih ¹ , Wei-Chong Lee ¹ , Cheng-Ya Yang ¹ , Yun-Ching Hung ¹ , Yung-Sheng Lin ¹ , Chen-Chao Wang ¹ , Chin-Pin Hung ¹ , C. Kao ¹ , Department of Materials Science and Engineering, National Taiwan University, Advanced Semiconductor Engineering, Inc., Taiwan	16TE1: Materials-3 16TE1-1 Development of a High-Resolution, High-Reliability Photo-Imageable Dielectric Kohhei Abe, Ryo Yukioka, Takeshi Nojiri, Eri Miyazawa, Takashi Kawamori, Resonac Corporation 16TE1-2 Low-temperature Sintering Accelerating of Silver Micro-flake for Improving Interconnect Characteristics by Designing Aliphatic Epoxy-based Binder Takanori Fukushima ^{1,2} , Masahiro Inoue ¹ , Gunma University, Research Fellow of Japan Society for the Promotion of Science 16TE1-3 Shrinkage Behaviour and Electrical Resistivity of Polyvalued Carbon Lattice Yu-Yen Chen ¹ , Hiroaki Tatsumi ¹ , Hiroshi Nishikawa ¹ , Graduate School of Engineering, The University of Osaka, ¹ Joining and Welding Research Institute, The University of Osaka 16TE1-4 Stretchable PEDOT/PSS Films with Enhanced Electrical and Mechanical Properties for Printed Electronics Masahiro Inoue, Hideyo Shimizu, Gunma University	16TF1: Thermal Management-1 16TF1-1 <Session Invited> High thermal conductive composite for efficient heat spreading through multi-dimensions strategy Bin Xu, Junichiro Shiomi, University of Tokyo 16TF1-2 Diamond Thermal Solutions for Emerging High-Heat-Flux and High-Power Semiconductor Packaging Yonhwa Tzeng ^{1,2} , National Cheng Kung University, ² National Tsinghua University 16TF1-3 Ag-coated Ni Metalization for Fluxless Indium-Based Tin Bonding Yuan-Jian Kui ¹ , Cheng-Yan Yang ¹ , Yu-Hsiang Lu ¹ , C. Robert Kao ² , National Taiwan University, ² National Taiwan University 16TF1-4 Thermal properties of Vertically Aligned Carbon Nanotube-based Thermal Interface Materials Yuki Inoue, Tomoki Okumura, Yamato Watanabe, Takayuki Nakano, Shizuoka University	
11:10							
11:25	16TA2: Glass PKG-2 16TA2-1 <Session Invited> TBD Glass PLP-HVM solution Frank Su, Lam Research 16TA2-2 <Session Invited> Reliability Evaluation of 40 µm-Pitch Solder Joint on Glass Interposer Naoko Kato, IBM 16TA2-3 <Session Invited> Process Control Innovations for Glass in Advanced Packaging Monita Pan, Onto 16TA2-4 <Session Invited> Next Generation High Efficiency Packaging Study Usunomiya, Interconnection Tech	16TB2: ISMP-2 16TB2-1 <Session Invited> Reliability of Fine-Pitch Reliability Layers (RDLs) for Advanced Packaging Prof. Young-Chang Joo, Department of Materials Science and Engineering, Seoul National University 16TB2-2 <Session Invited> Novel Electrochemical Processes for Advanced Packaging Prof. Bongyoung Yoo, Department of Materials and Chemical Engineering, Hanyang University, ERICA 16TB2-3 Non-Invasive Visualization of Corrosion in Electronic Packages Using a Conditional Diffusion Model Trained on S-Parameters Tae-Yeon Kang, The University of Suwon 16TB2-4 Clustering-Enhanced Deep Surrogate Model for Global Stress and Weak-Point Detection in Semiconductor Packaging Boo Soo Ma ¹ , Boyeon Kim ¹ , Myoung Song ¹ , Tae-Yeon Kang ¹ , Taek-Soo Kim ¹ , University of Suwon, ¹ Korea Advanced Institute of Science and Technology (KAIST)	16TC2: Direct Bonding 16TC2-1 A Process-Chemistry Map for Room-Temperature Dielectric Bonding Yun-Hsuan Chen ¹ , Guanyu Song ¹ , Cheng-Chieh Kao ¹ , Chih Chen ¹ , National Yang Ming Chiao Tung University, ¹ Lam Research Corporation 16TC2-2 A Comparison Study on Room Temperature Bonding of Sapphire-Sapphire and Al203 Film-Al203 Film Kenji Uno, Ryō Takigawa, Graduate School of Information Science and Electrical Engineering, Kyushu University 16TC2-3 Study on Surface Uniformity Improvement of Ag Nanolayer Formed by Galvanic Deposition Quan-Wei Yin, Cheng-Min Yen, Shih-kang Lin, National Cheng Kung University 16TC2-4 Heterogeneous Integration of LiNbO ₃ and Si Dies Using Room-Temperature Au-Au Bonding in Ambient Air With O ₂ Plasma Treatment Matsunobu Kosei, Takigawa Ryo, Kyushu University	16TD2: Others 16TD2-1 Reliability Assessment of Hybrid Bonding Interconnects under Electromigration Stress Min-Yan Tsai, Shan-Bo Wang, Ying-Sheng Lin, Yu-Ren Chang, Chieh-Ming Hsu, Chih-Jung Hsu, Zhao-Ze Jiang, Chen-Chao Wang, Chin-Pin Hung 16TD2-2 Enhanced electromigration resistance by nanowire Cu-Ag Interconnects for advanced packaging Fan-Yi Ouyang, Peng-Hsiang Hsu, National Tsing Hua University 16TD2-3 Characterization for the Bottom Joint of Stacked Micro-Vias Integrated in the Substrate by ToF-SIMS and STEM Masahiro Yamashita ¹ , Ming-Chun Hsieh ^{1,3} , Rieko Okumura ¹ , Hiroyoshi Yoshida ¹ , Cuantong Chen ¹ , Hiroki Seto ¹ , Kei Hashizume ¹ , kimihiko yamanaka ¹ , Hiroshi Nishikawa ¹ , Katsuki Suganuma ¹ , ¹ SANKEN, The University of Osaka, ² Okuno Chemical Industries Co., Ltd, ³ JWRI, The University of Osaka 16TD2-4 Corrosion Behavior of Cu-to-Cu Direct Bonding by Refil Friction Stir Spot Welding for Bus Bar Application HAYOUNG YU ^{1,2} , Myoung-Gyu Lee ¹ , Dongjin Kim ¹ , Korea Institute of Industrial Technology (KITECH), ¹ Seoul National University	16TE2: Materials-4 16TE2-1 Low-Temperature Sintering of Cu Microparticle/Cu ₃ O Nanoparticle Composite Pastes for High-Strength Bonding ¹ Tetsu Yonezawa ¹ , Takashi Aso ¹ , Hokkaido University, ¹ Chulalongkorn University 16TE2-2 Nickel-Enhanced Copper Complex Inks With Improved Weather Resistance Zheng Yi ¹ , Tsukamoto Hiroki ¹ , Yonezawa Takaaki ^{1,2} , ¹ Division of Materials Science and Engineering, Hokkaido University, ² Department of Chemical Engineering, Chulalongkorn University 16TE2-3 High-Strength Cu Joint Fabricated Using Bimodal-Sized Cu Nanoparticles Qianhua Zhu ¹ , Tetsu Yonezawa, Faculty of Engineering, Hokkaido University 16TE2-4 Surface Modification of Fine Grain Copper for Low Temperature Hybrid Bonding Taiki Miyamoto ¹ , Kentai Hayama ¹ , Fabiana Tanaka ¹ , Wei-Tsui Kamija ¹ , Marie Sano ¹ , Ryota Nakao ¹ , Ryo Tanaka ¹ , Fumihiro Inoue ¹ , Yokohama National University, ¹ Okuno Chemical Industries Co., Ltd. 16TE2-5 On the Temperature Measurement of on-state GaN-HEMT by Raman Spectroscopy Kensuke Sagawa ¹ , Kuniharu Kobashi ^{1,2} , Si-Meng Chen ¹ , Takeyu Hoshii ^{1,2} , Anton Myalitsin ^{1,2} , Hiroyuki Ryoson ¹ , Takashi Yoda ¹ , Takayuki Ohba ¹ , Kuniyuki Kakushima ^{1,2} , ¹ Institute of Science Tokyo, ² WOW Alliance, Institute of Science Tokyo, ¹ ANVOS Analytics Co., Ltd.	16TF2: Thermal Management-2 16TF2-1 Room-Temperature Wafer Direct InP/SiC Bonding Via Surface Activated Bonding Method JUMPEI NAKAMURA, Ryo Takigawa, Kyushu-University 16TF2-2 Development of high heat dissipation insulated metal substrates using thin insulating films YUKIHIRO WATANABE ¹ , Misuru Nishimura ¹ , Yasuyuki Yanase ¹ , Kenzo Usami ¹ , Yutaka Takagi ¹ , Katsuyuki Sakata ¹ , Keiji Takagi ¹ , Akiyoshi Hattori ¹ , Niterra Co., Ltd., ² NTK Ceramic Co., Ltd. 16TF2-3 On the Temperature Measurement of on-state GaN-HEMT by Raman Spectroscopy Kensuke Sagawa ¹ , Kuniharu Kobashi ^{1,2} , Si-Meng Chen ¹ , Takeyu Hoshii ^{1,2} , Anton Myalitsin ^{1,2} , Hiroyuki Ryoson ¹ , Takashi Yoda ¹ , Takayuki Ohba ¹ , Kuniyuki Kakushima ^{1,2} , ¹ Institute of Science Tokyo, ² WOW Alliance, Institute of Science Tokyo, ¹ ANVOS Analytics Co., Ltd.	
13:05							
13:55	16TA3: PLP 16TA3-1 <Session Invited> TBD TBD, Samsung Electronics 16TA3-2 <Session Invited> Experience-Driven Advanced Digital Lithography System for Panel Applications Yusuke MATSUHASHI, Nikon 16TA3-3 <Session Invited> Considerations for Implementing CMP in Panel-Level Packaging Haedo JEONG, Pusan National University 16TA3-4 <Session Invited> Cutting edge 3D-IC design and analysis environment: Unified solution accelerates advanced package design with AI and Cloud Ksenia ROZE, Cadence	16TB3: SMIA 16TB3-1 <Session Invited> Glass/LTCC Composite Substrates as Completely Inorganic Packaging Interposer Jens Mueller, Technische Universität Ilmenau 16TB3-2 <Session Invited> Robust Ceramic Components and Packages for EUV Lithography Systems Markus Eberstein, ASML 16TB3-3 <Session Invited> LIFT (Laser-Induced Forward Transfer) Application to SMT Manufacturing Markus Bohrer, Dr. Bohrer LaserTec GmbH	16TC3: Process Development-1 16TC3-1 Heterogeneous device structure without underfill composed with submicron gold particle bump and seal by chip on wafer process Takashi Imahigashi, Sony Semiconductor Manufacturing Corp. 16TC3-2 Design for Functional Resin Filling Process in Direct Nanoimprint Lithography Ryuhei Yamamura ¹ , Atsushi Mochida ¹ , Daisuke Sakurai ¹ , Masaya Yasuda ¹ , Yoshihiko Hirai ¹ , Panasonic Holdings Corporation, Graduate School of Engineering, Osaka Metropolitan University 16TC3-3 Method for Predicting the Impact of Manufacturing Variations Using S-Parameters Satoshi Nakamura, Aki Tanaka, KYOCERA Corporation 16TC3-4 Fine-pitch Copper Wiring Formation on Build-up Film fabricated by Silver-seed Semi-Additive Process Wataru Fujikawa, Akira Murakawa, Shota Niihbayashi, Akirori Furutani, Norimasa Fukazawa, Rei Tamura, DIC Corporation	16TD3: DMR-E 16TD3-1 Signal Integrity and Mechanical Design for Mounting HBM4 on an Organic Interposer Taishi Yamaguchi, Yuji Nakumoto, Hanuki Horikoshi, Manabu Nakamura, SHINKO ELECTRIC INDUSTRIES CO., LTD. 16TD3-2 Methods for Extracting the Electrical Characteristics of FC-BGA Packages under Thermal Conditions Aki Tanaka, Satoshi Nakamura, KYOCERA Corporation 16TD3-3 Method for Predicting the Impact of Manufacturing Variations Using S-Parameters Satoshi Nakamura, Aki Tanaka, KYOCERA Corporation 16TD3-4 Study on Acceleration of Preconditioning for Solderability Testing Takaaki Sensui, Hideyuki Nagai, TDK Corporation	16TE3: Materials-5 16TE3-1 Influence of Indium on the Strength, Ductility, and Soldering of Sn-Bi Alloys CHIH-HSIANG LIU, Tzu-Hsiang Liao, Jia-Xiang Gao, Yu-An Shen, Feng Chia University 16TE3-2 Minor Indium Additions to Sn-Bi Alloys - Properties and Corrosion JIA-XIANG GAO, Chih-Hsiang Liao, Tzu-Hsiang Liao, Yu-An Shen, Feng Chia University 16TE3-3 Microstructural Refinement and Solidification Behavior in Sn-In Composite Solders with NiO-Coated ZrO ₂ Nanoparticles Shunji Nitta ¹ , Hiroaki Tatsumi ¹ , Atsushi Ito ^{1,2} , Arimichi Takayama ¹ , Hiroshi Nishikawa ¹ , ¹ Graduate School of Engineering, The University of Osaka, ² Joining and Welding Research Institute, The University of Osaka, ¹ National Institute for Fusion Science, ² The Graduate University for Advanced Studies 16TE3-4 In-situ observation of Cu ₂ Sn dissolution in low temperature In-Sn-Bi alloys Jiye Zhou, Xin Fu Tan, Stuart McDonald, Kazuhiko Nogita, The University of Queensland	16TF3: Thermal Management-3 16TF3-1 A Review of a New Thermal Conductivity Measurement Methodology Tomoko Kara ¹ , Qun Yuan ¹ , Haifeng Xu ¹ , Shuhui Fukunaga ¹ , Toshiyuki Funaki ¹ , THERDEAU CO., LTD., ² Luehco, Co., LTD., ³ The University of Osaka 16TF3-2 Investigating the Thermal Resistance of the Si and Epoxy Interface Wei-Cheng Huang, Lev Tseng, Bo-Yu Huang, Meng-Hsueh Yang, Hui-Chung Liu, ACE Group Chung-Li Branch 16TF3-3 Cooling Performance Improvement of Heat Sinks by Utilizing Thermal Impedance Distribution Koji Nishi, Ashikaga University 16TF3-4 From Package to Power Integration Enhancing Energy Efficiency through Improved Thermal Dissipation Chesheng Kung, Hao Yu Lu, Micron Memory Taiwan	
15:35							
15:50	16TA4: HIR 16TA4-1 <Session Invited> TBD	16TB4: Setouchi 16TB4-1 <Session Invited> Si-based optical interface devices for photonic-electronics convergence technology (tentative) Hirotaka Gotoh, Hiroshima University 16TB4-2 <Session Invited> SIC CMOS Integrated Circuits and Image Sensors for Extreme Environment Applications Shin-Ichiro Kuroki, Hiroshima University 16TB4-3 <Session Invited> Challenge & Opportunity for Advanced Packaging Takashi Hayakawa, Tokyo Electron 16TB4-4 <Session Invited> TBD	16TC4: Process Development-2 16TC4-1 Study on the Blind Via Hole Metallization Method for High-Speed Transmission Using Hybrid Desmear and High-Reliability Electroless Copper Plating Tomoya Sawada, Okuno chemical industries 16TC4-2 Interfacial Reactions in the Cu/Sn/NI Sandwhich Couples in 3D IC Packaging Yen-Ling Chen ¹ , Shih-Jung Chai ² , Yee-Wen Yen ² , ¹ National Taiwan University of Science and Technology for Materials Science and Engineering, ² National Taiwan University of Science and Technology for Sustainable Electrochemical Energy Development Center 16TC4-3 Optimization of Encapsulation process for Advanced package usage simulation KAZUKI NOGUUCHI, Shien Leo, Osaka 16TC4-4 Accurate identification of submicron-sized particle on a copper substrate Michael Lo ¹ , Naoki Bader ¹ , Photothermal Spectroscopy Corp., ¹ Nihon Thermal Consulting	16TD4: Mech simulation-1 16TD4-1 Multiphysics Analysis of Magnetic Thin-Film Inductors Yung-Ching Chao ¹ , Ting-Sheng Chang ¹ , De-Shin Liu ¹ , ¹ National Chiayi University, ¹ National Chung Cheng University 16TD4-2 Advanced Simulation Techniques for Predicting Warpage Behavior in Automotive Electronic Assemblies Wen-Chih Yang ^{1,2} , Yang-Shen Yu ¹ , Chan-Chieh Lee ¹ , Chang-Chun Lin ¹ , ¹ WNC CORP., ² WNC Hua University 16TD4-3 Systematically Optimized Ensemble Stacking Warpage Simulation Development for PCB Packaging in AI Drives under Reliability Conditions Shifa Zehrauddin Desai ¹ , Yan-Yu Liu ¹ , Ming-Chang Wu ¹ , Chen-Chou Tsai ¹ , Chieh-Yu Ma ¹ , Xi-Hong Chen ¹ , Chih-Cheng Tsai ¹ , Wen-Chen Wu ¹ , Chang-Chun Lee ¹ , Department of Power Mechanical Engineering, National Tsing Hua University, ¹ Wistron Corporation 16TD4-4 Machine Learning-Based Prediction of PCB Warpage in AI Drives under Reliability Conditions Shifa Zehrauddin Desai ¹ , Yan-Yu Liu ¹ , Ming-Chang Wu ¹ , Chen-Chou Tsai ¹ , Chieh-Yu Ma ¹ , Xi-Hong Chen ¹ , Chih-Cheng Tsai ¹ , Wen-Chen Wu ¹ , Chang-Chun Lee ¹ , Department of Power Mechanical Engineering, National Tsing Hua University, ¹ Wistron Corporation	16TE4: Materials-6 16TE4-1 Tensile properties of Sn-37Bi-0.5Sb-0.5Cu-0.03Ni low-temperature soldering alloy Xiao-Zhao Lo ¹ , Stuart McDonald ¹ , Xian Fu ¹ , Takatoshi Nishimura ¹ , Kazuhiro Nogita ¹ , The University of Queensland, ¹ Nihon Superior Co., Ltd 16TE4-2 In-situ SEM Investigation of Solder Deformation of Various Sn _x Bi _y Solder Alloys Yi-Hsiang Yen ¹ , Yu-Hsin Lin ¹ , C. Kao, Department of Materials Science and Engineering, National Taiwan University 16TE4-3 Effect of Sn Addition on the Tensile and Creep Properties of Sn-(58-x)Bi _x Sn Low-Temperature Solders Zhi Ai, Yu-chen Liu, National Cheng Kung University 16TE4-4 Effect of Thermal Properties of Dielectric Liquids on Breathing Phenomenon Induced by Lotus-Type Porous Copper Toshiyuki Okafuji, Takuja Ide ¹ , Koei Yuki ¹ , Tetsuro Ogushi ¹ , Masaaki Murakami ¹ , Kazuhisa Yuki ¹ , ¹ Tokyo University of Science-Yamaguchi, ¹ Lotsu Thermal Solution Inc. 16TE4-5 Metal 3D Printed Multilayer Channel Liquid Cooling Plate for Large-Scale Heat Dissipation Huang-Chih Lin ¹ , Jia-Tu ¹ , Zhen Yang ¹ , Haoyang Sun ¹ , Fan-Ji ¹ , Jia-Jie Kang ¹ , Chi-Zhang ¹ , Wei Wang ¹ , ¹ Peking University, ¹ China University of Geosciences (Beijing), Beijing Institute of Remote Sensing Equipment, ¹ National Key Laboratory of Advanced Micro and Nano Manufacture Technology	16TF4: Thermal Management-4 16TF4-1 Design and Evaluation of Microchannel Cooling Modules for 2.5D Multi-Hotspot High-Power Packages Yi-hao Lo ¹ , Jun Mizuno ¹ , Hsuan-hao Chang ¹ , Yu-Ting Wu ¹ , Muhammad Firdaus ¹ , Chi-Hua Yu ¹ , Takeshi Miyamoto ¹ , Hung-Hsien Huang ¹ , ¹ National Cheng Kung University, ¹ Advanced Semiconductor Engineering, ¹ Chiba University 16TF4-2 Maximized Manufacturing Flexibility and Convective Heat Transfer Characteristics of Direct Cooling Method for Use in Large-Area Power Electronics Heatsink Byeongchan Kim ^{1,2} , Ha-Young Yu ¹ , Junha Baik ¹ , Dongjin Kim ¹ , ¹ Korea institute of industrial technology, ² Korea university 16TF4-3 Effect of Thermal Properties of Dielectric Liquids on Breathing Phenomenon Induced by Lotus-Type Porous Copper Toshiyuki Okafuji, Takuja Ide ¹ , Koei Yuki ¹ , Tetsuro Ogushi ¹ , Masaaki Murakami ¹ , Kazuhisa Yuki ¹ , ¹ Tokyo University of Science-Yamaguchi, ¹ Lotsu Thermal Solution Inc. 16TF4-4 Metal 3D Printed Multilayer Channel Liquid Cooling Plate for Large-Scale Heat Dissipation Huang-Chih Lin ¹ , Jia-Tu ¹ , Zhen Yang ¹ , Haoyang Sun ¹ , Fan-Ji ¹ , Jia-Jie Kang ¹ , Chi-Zhang ¹ , Wei Wang ¹ , ¹ Peking University, ¹ China University of Geosciences (Beijing), Beijing Institute of Remote Sensing Equipment, ¹ National Key Laboratory of Advanced Micro and Nano Manufacture Technology	
17:30							
18:45							
19:00							
			Poster Session				
			Sponsor's Exhibition Party				